
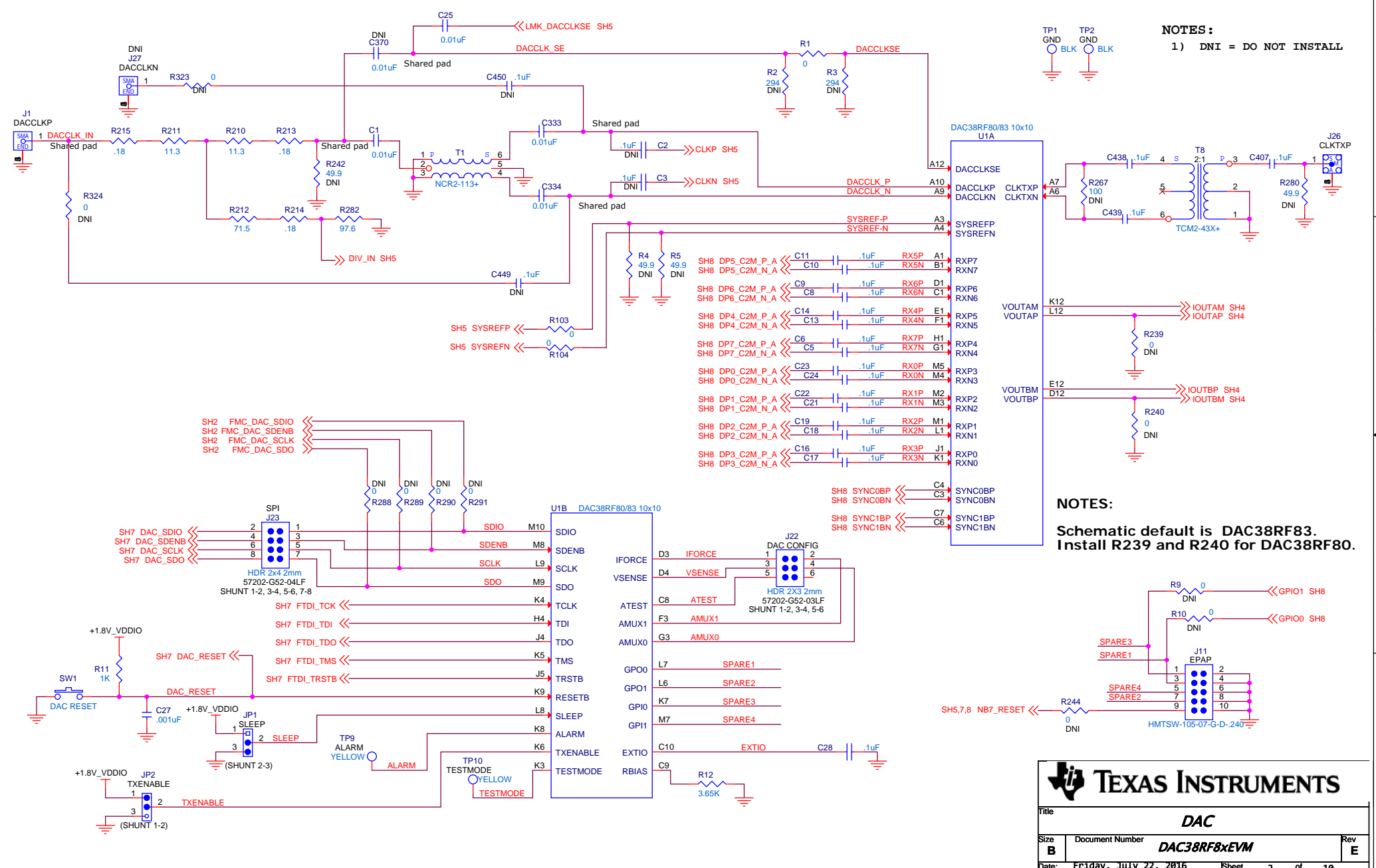


TIDA-01084

 TEXAS INSTRUMENTS		Title	
		COVER	
Drawn: L NGUYEN 02/2016	Size B	Document Number	Rev E
Engineer: E DWOBENG 02/2016		DAC38RF8xEVM	
Date: Tuesday, March 01, 2016		Sheet	1 of 10

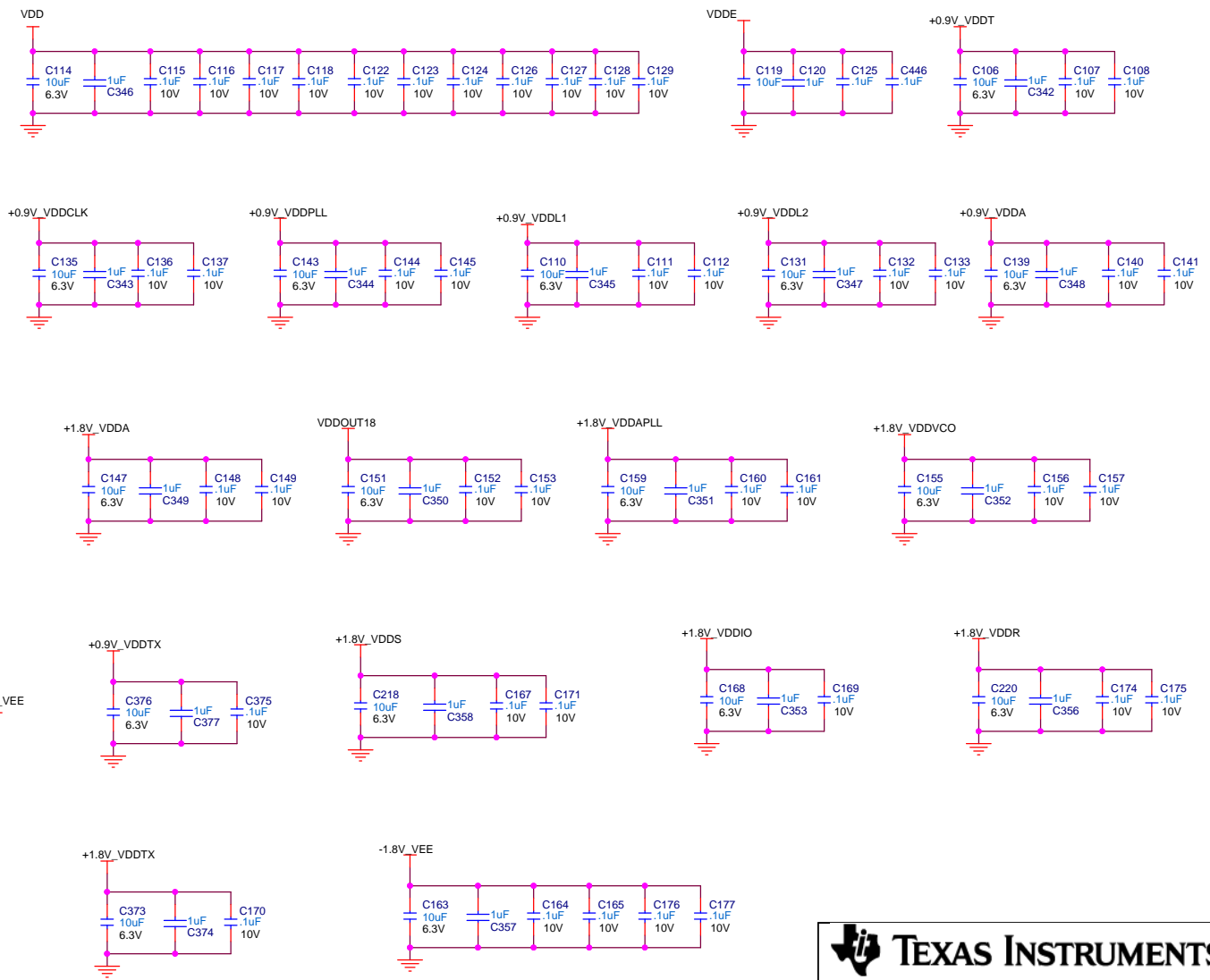
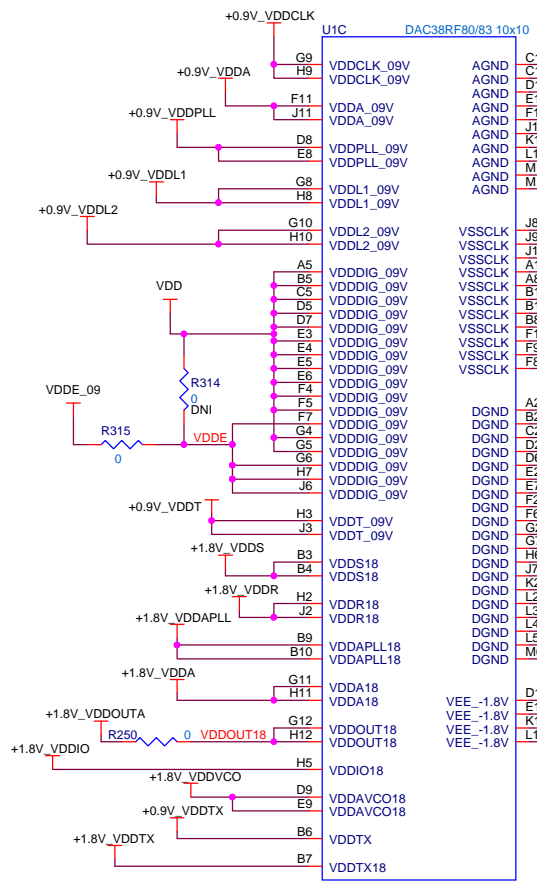


TEXAS INSTRUMENTS

Title: **DAC**

Size: **B** Document Number: **DAC38RF8xEVM** Rev: **E**

Date: **Fri, July 22, 2016** Sheet: **2** of **10**

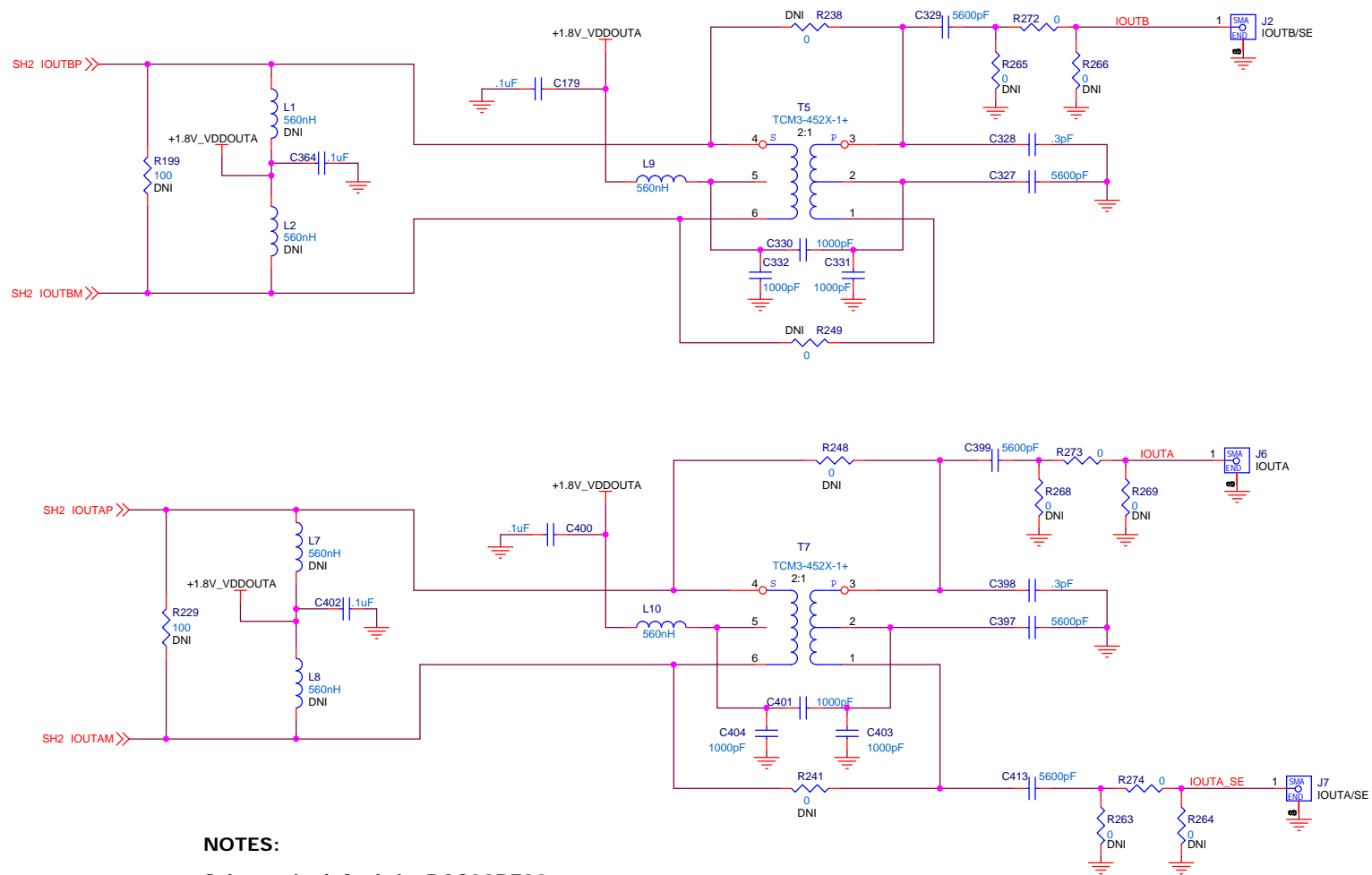


TEXAS INSTRUMENTS

Title: **DAC POWER**

Size **B** Document Number **DAC38RF8xEVM** Rev **E**

Date: **Tuesday, March 01, 2016** Sheet **3** of **10**



NOTES:

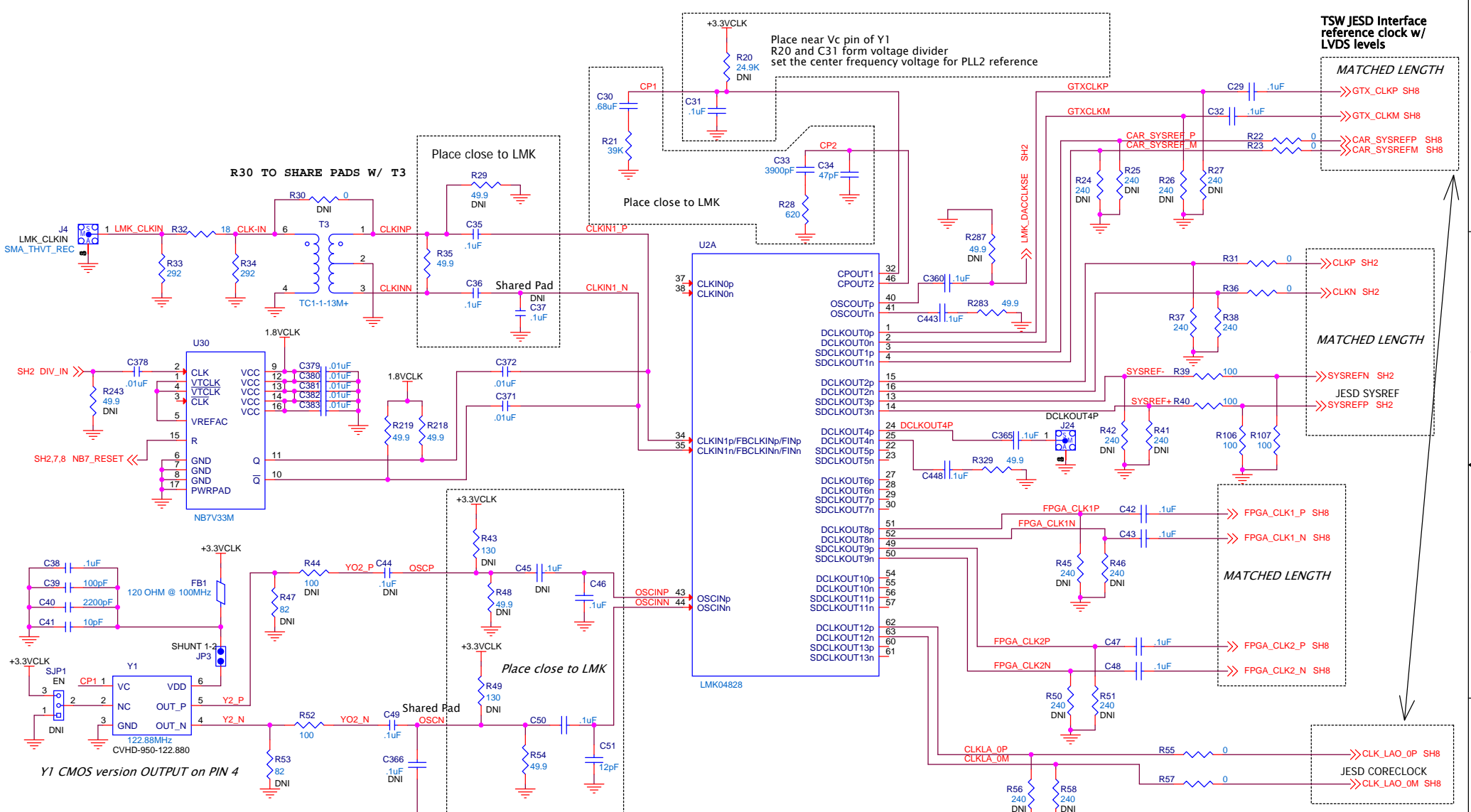
Schematic default is DAC38RF83.

For DAC38RF80:

Install R238, R241
 DNI C179, C400, L9, L10, T5, T7, C330, C331, C332,
 C401, C403, C404, C328, C327, C399, R273,
 C398, C397, J6

TEXAS INSTRUMENTS

Title		DAC OUTPUT	
Size	Document Number	Rev	
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TSW JESD Interface reference clock w/ LVDS levels

MATCHED LENGTH

GTX_CLKP SH8
GTX_CLKM SH8
CAR_SYSREFP SH8
CAR_SYSREFM SH8

MATCHED LENGTH

CLKP SH2
CLKN SH2
SYSREFN SH2
JESD SYSREF
SYSREFP SH2

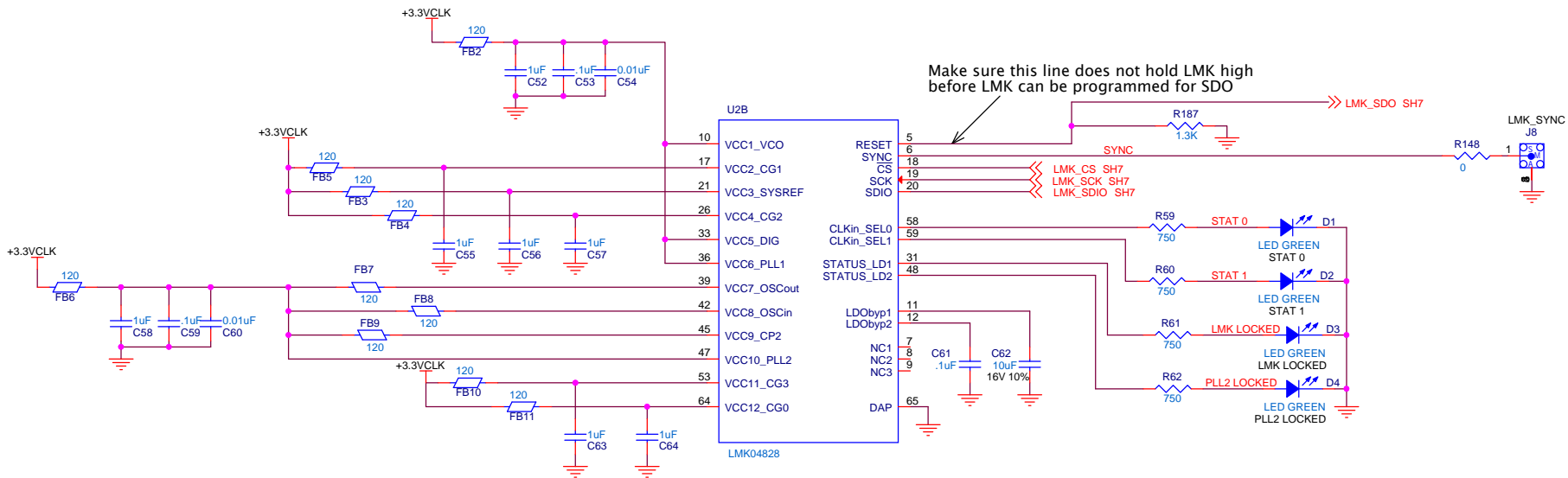
MATCHED LENGTH

FPGA_CLK1P SH8
FPGA_CLK1N SH8
FPGA_CLK2P SH8
FPGA_CLK2N SH8

CLKLA_OP SH8
JESD CORECLOCK
CLKLA_OM SH8



Title			LMK		
Size	Document Number				Rev
B	DAC38RF8xEVM				E
Date:	Friday, July 22, 2016	Sheet	5	of	10

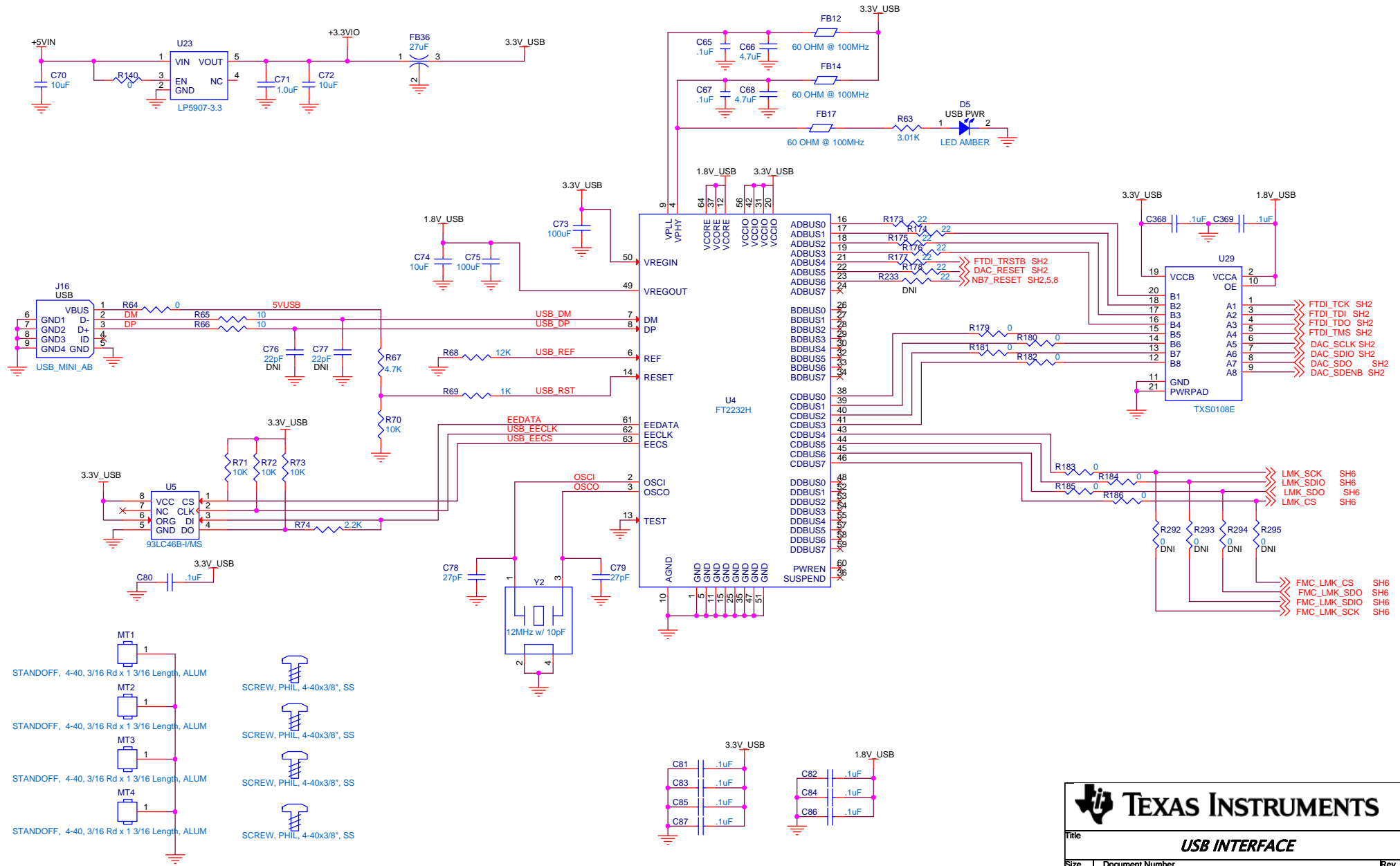


TEXAS INSTRUMENTS

Title: **LMK**

Size: **B** Document Number: **DAC38RF8xEVM** Rev: **E**

Date: **Tuesday, March 01, 2016** Sheet: **6** of **10**

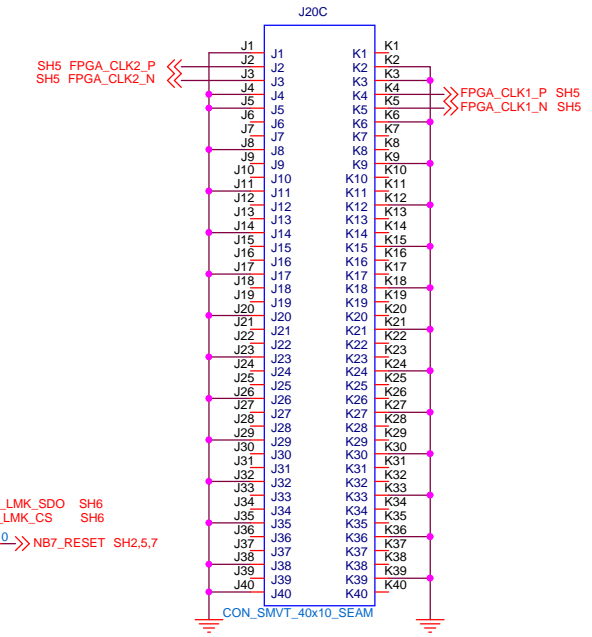
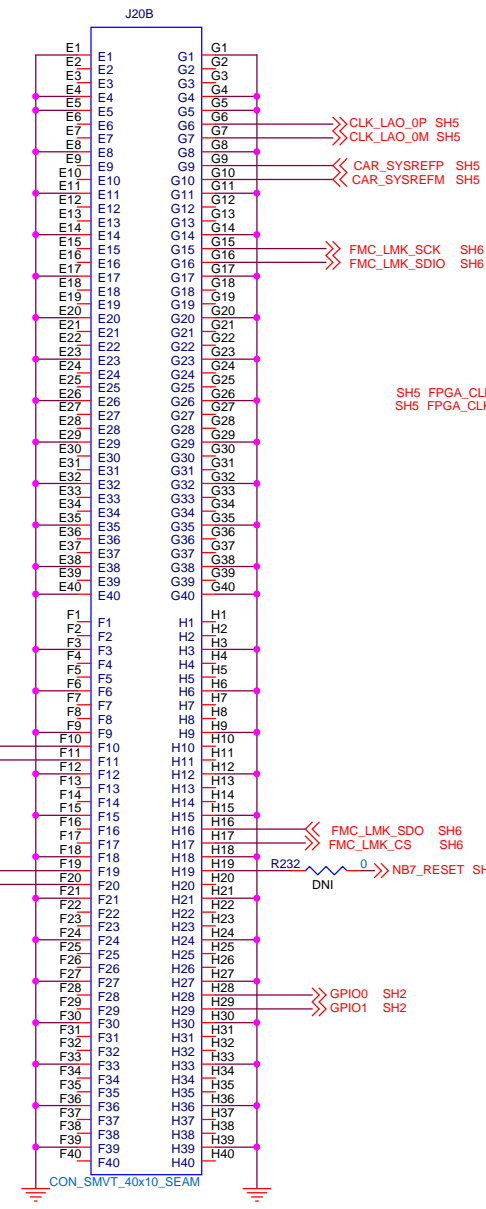
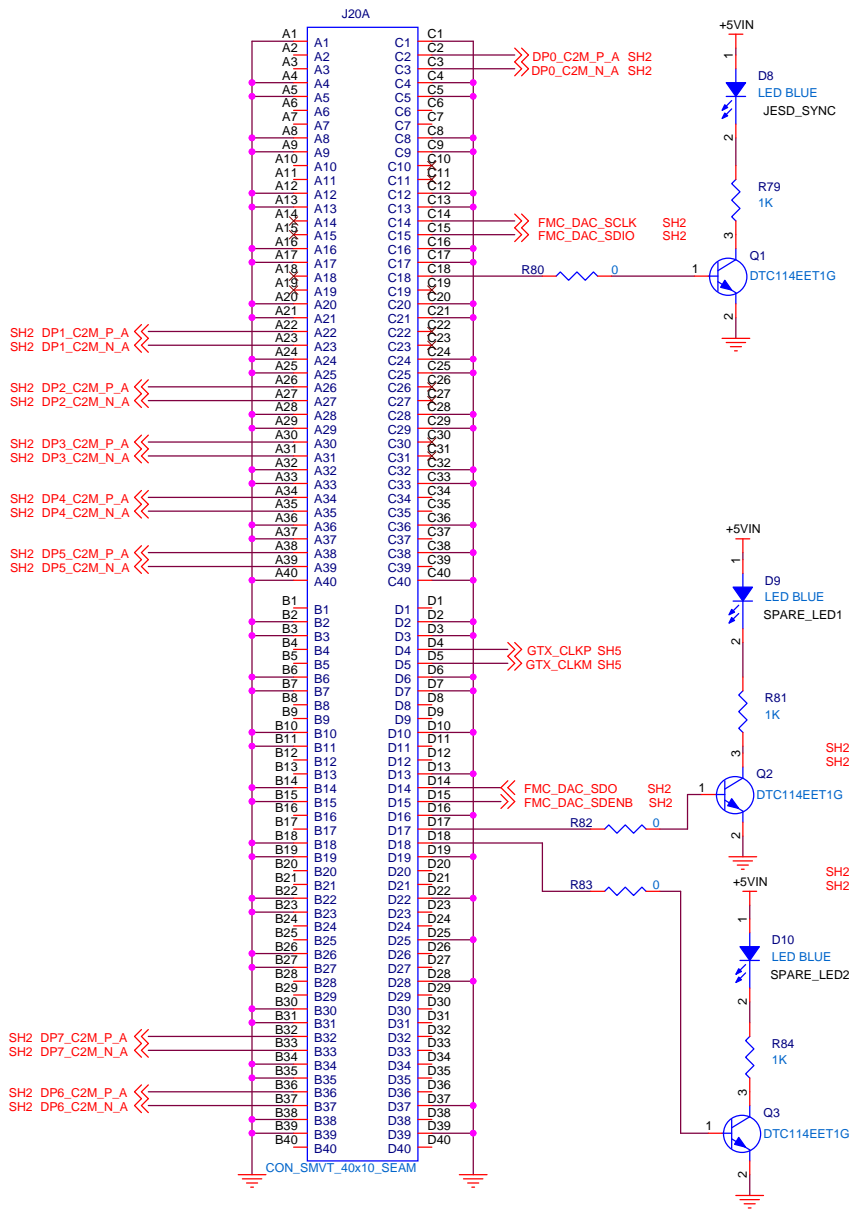


TEXAS INSTRUMENTS

Title: **USB INTERFACE**

Size **B** Document Number **DAC38RF8xEVM** Rev **E**

Date: **Thursday, March 03, 2016** Sheet **7** of **10**



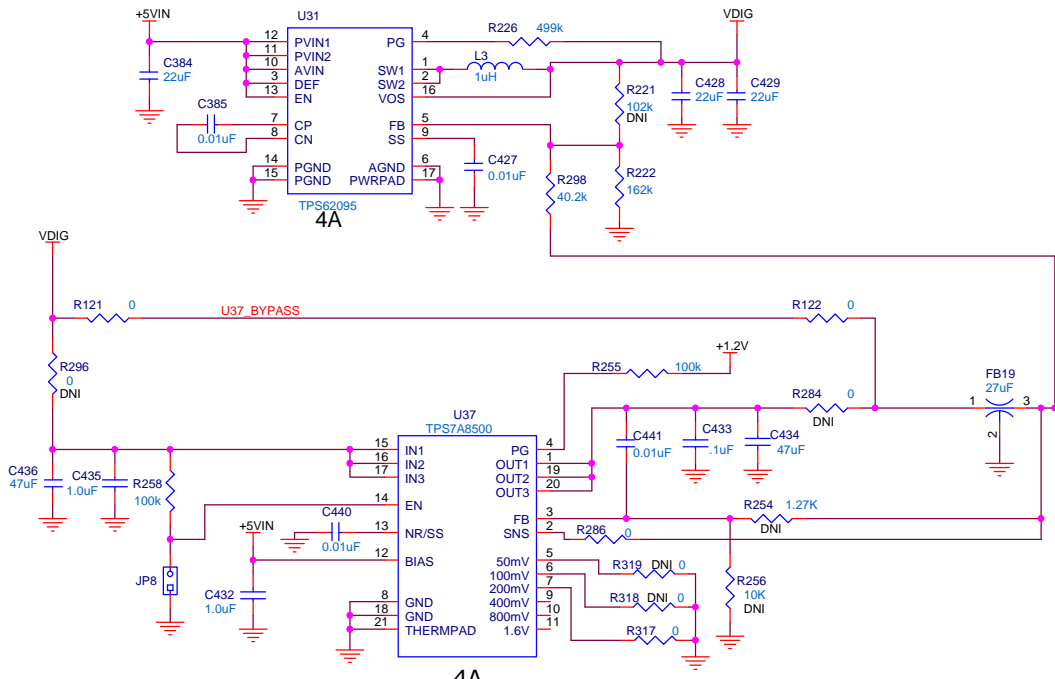
TEXAS INSTRUMENTS

Title: 12500 TI Boulevard, Dallas, Texas 75243

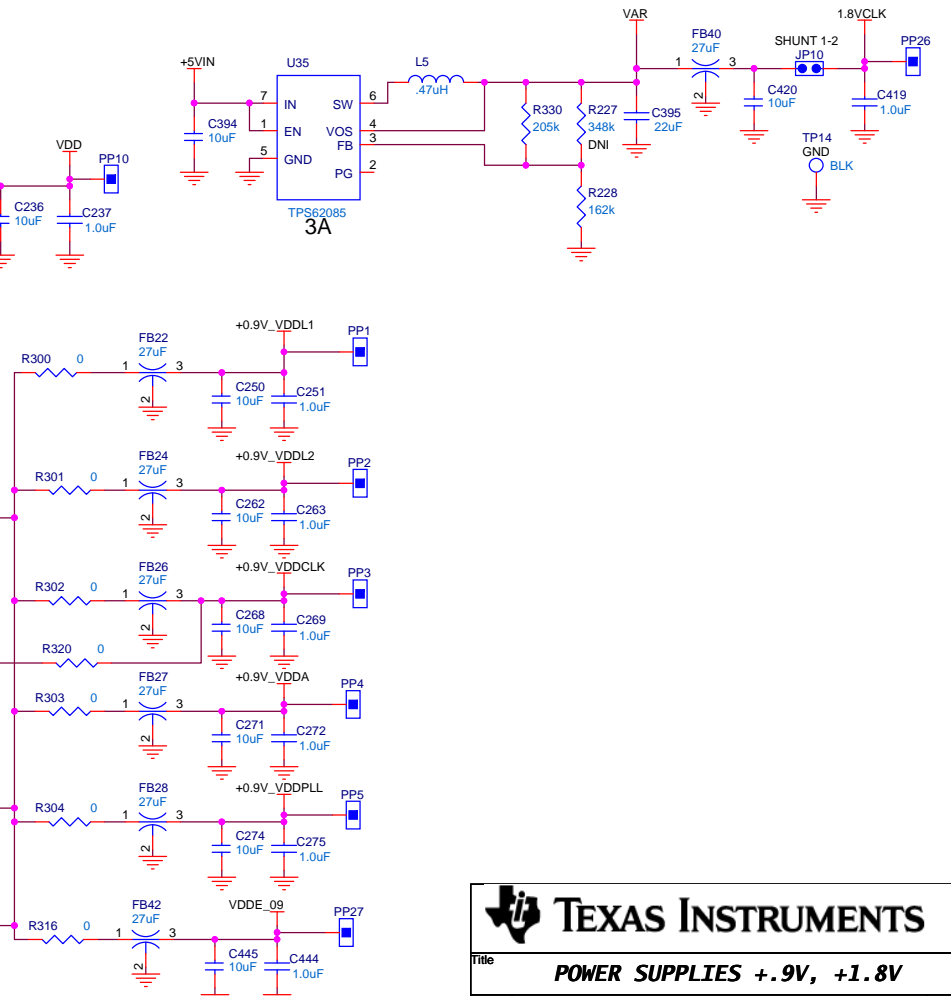
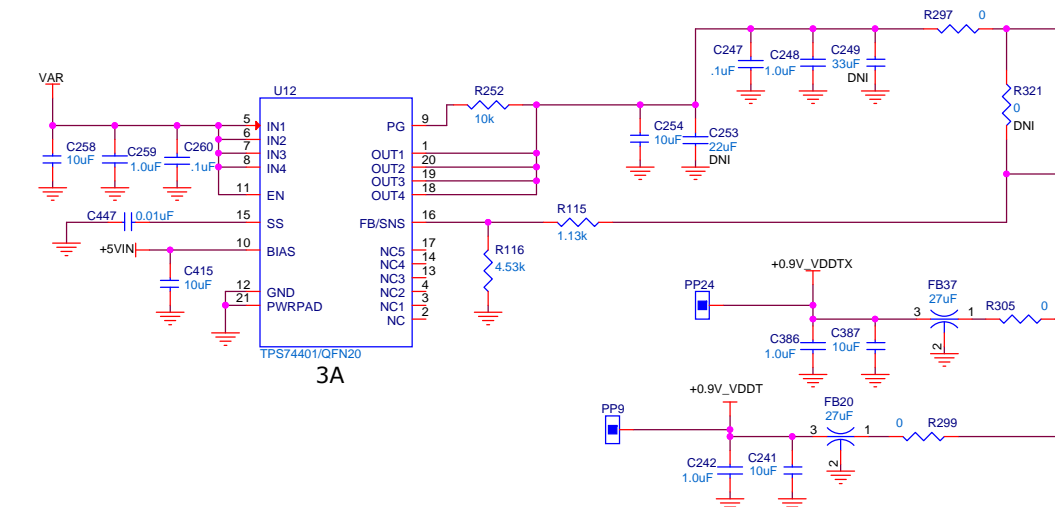
FMC

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NOTES:
 To bypass LDO U37: Install R298, R121, R122
 DNI R221, R296, R284
 To use LDO U34 (U35 output = 2.5V): DNI R330
 Install R227

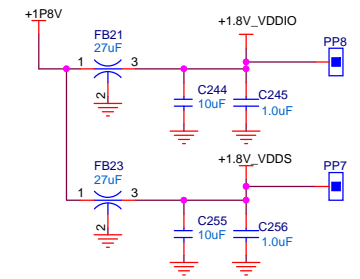
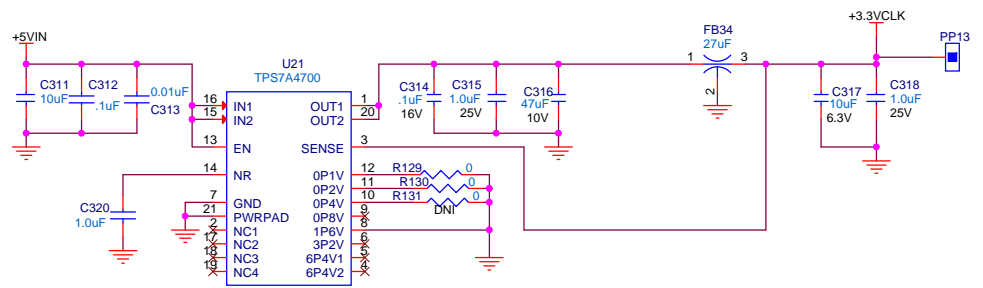
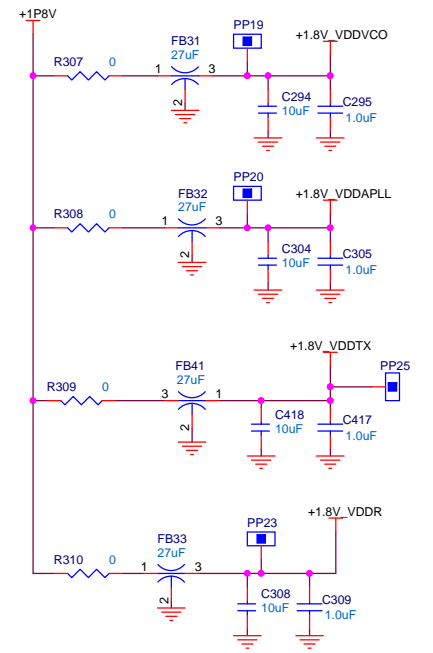
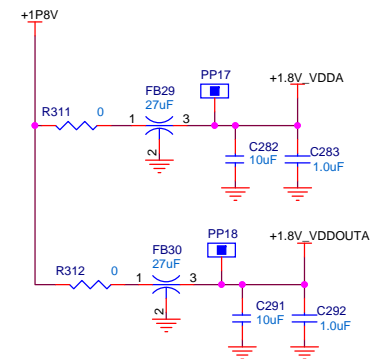
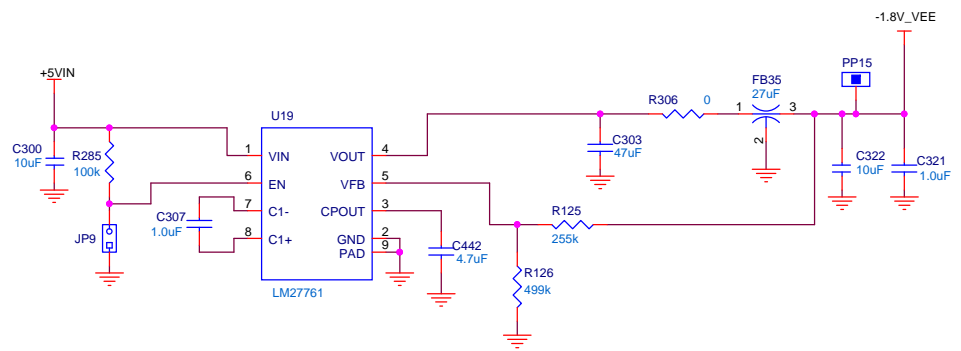
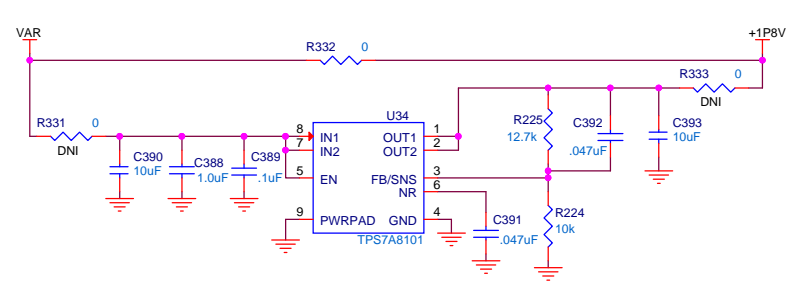
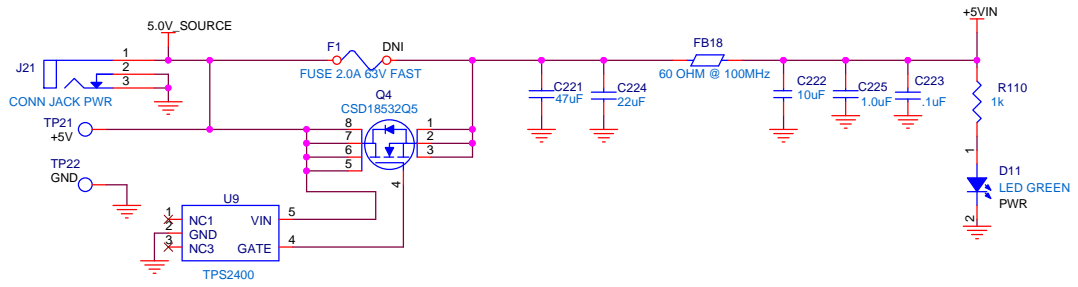


TEXAS INSTRUMENTS

Title: **POWER SUPPLIES +.9V, +1.8V**

Size **B** Document Number **DAC38RF8xEVM** Rev **E**

Date: Tuesday, March 01, 2016 Sheet 9 of 10



TEXAS INSTRUMENTS

Title: **POWER SUPPLIES**

Size **B** Document Number: **DAC38RF8xEVM** Rev **E**

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